

# Ge-on-Si photodetector array for sensitive infrared imaging

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## Main goal

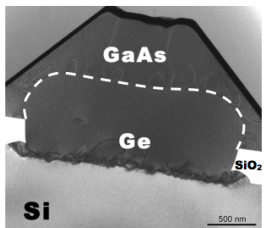
- Create a Germanium PD array
- Near-infrared detection range

## Why Ge-on-Si

- Ge bandgap of 0.67eV
- Suitable for near-infrared applications

## What has been done

- Single Ge-on-Si diodes fabricated and tested
- 300x1 Ge line arrays fabricated and tested

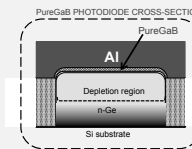
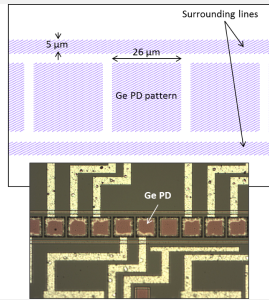
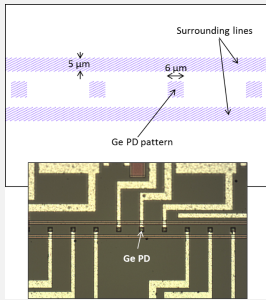
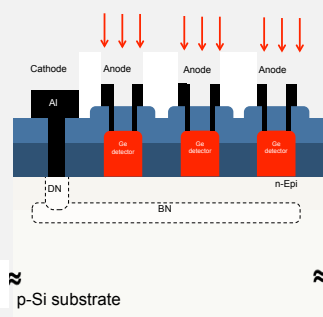


Cross-sectional TEM images of selective Ge epitaxy grown on patterned Si followed by in-situ growth of a GaAs layer

## 300x1 Ge-on-Si Photodiode Array Process Flow

- Cross-sectional TEM image of selective Ge growth
- Schematic of the PureGaB Ge-on-Si photodetector arrays
- Ge deposition for low defect density Ge-on-Si island growth
- Ga deposition for ultrashallow p+n junction
- B deposition for good ohmic contacting of the p<sup>+</sup> Ge-island anode to an Al metal interconnect

## Front-side illumination

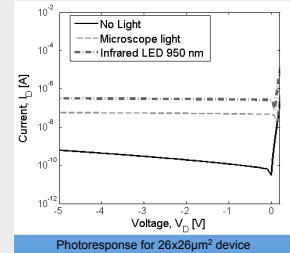
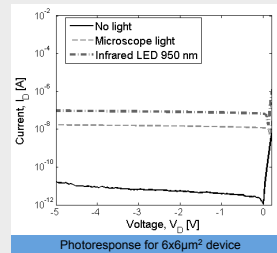
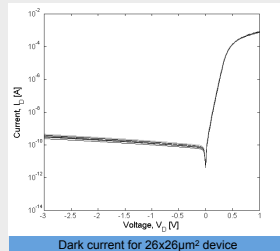
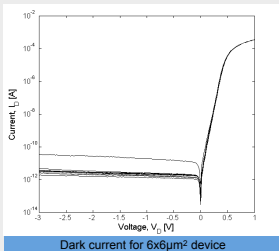


- Top-view cell of the Ge-PD design (top) and the microscopic-view of the fabricated arrays (bottom) with two sizes of a) 6x6 μm<sup>2</sup> and b) 26x26 μm<sup>2</sup>

## Ge-on-Si SPAD and Line Array Experimental Results

### Specifications of Ge Line Array

- 300x1 arrays of PureGaB Ge-PDs with 2 PD sizes of 6x6 μm<sup>2</sup> and 26x26 μm<sup>2</sup>
- Uniformity of the fabricated devices over the array in terms of I-V characteristics and photoresponses
- A new process module for metal removal on the Ge-islands,



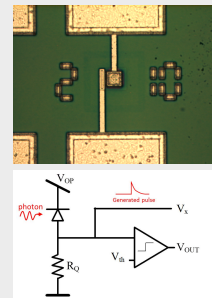
### Specifications of Ge APDs

- Can be operated both in proportional and in Geiger mode
- Low dark counts and reasonably high sensitivity at room temperature
- Low values of reverse current, series resistance and ideality factor

Performance (APD/linear mode)	Min.	Typ.	Max.	Unit
Active area	4		40	μm <sup>2</sup>
Breakdown voltage for 2x2 μm <sup>2</sup>	9			V
Breakdown voltage for 2x20 μm <sup>2</sup>			13	V
Breakdown voltage		11		V
Dark current @ 1V reverse bias	2		20	pA

Performance (Geiger mode)	Min.	Typ.	Max.	Unit
Excess bias voltage	0		4	V
DCR @ V <sub>e</sub> = 1V	10		60	kHz
I <sub>d</sub> /I <sub>ref</sub> @ V <sub>e</sub> =3V			25	%
FWHM Time jitter			900	ps

Performance summary



## Conclusion & Future Plans

- The fabricated detector array is operational in linear mode with high yield
- The device shows very good sensitivity to near infrared light with good I-V performance that is, to our knowledge, best in the literature

### Future work

- Improving the device to operate in SPAD mode
- Integrating the pre-amplification circuit in the same chip together with the device